

EAST - [thinsearch15.wsp:1]

FileViewEditToolsWindowHelp

BRS: 1 2

BRS:

BRS:

BRS: upside

Pending

Active

L1: (137) second adj leadframe

L2: (8) second adj lead-frame

L3: (691) second adj lead adj frame

L4: (309) 3 and thickness

L5: (19) "5313095"

L6: (1) 3 and 5

L7: (3) 1 and 5

Failed

USPAT:US:PGPUB:EPD:JPD:DERWENT:IBM:109

Default operator: OR

1 and 5

BRS form

ISAR form

Image

Text

HTML

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Cla	Inventor	S	C	P	3	Image Doi
1	<input type="checkbox"/>	<input type="checkbox"/>	US 5438021 A	19950801	14	Method of manufacturing a multiple-chip semiconductor device	438/107	257/E23.042; 257/E23.051;		Tagawa, Tomohide et al	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 543802
2	<input type="checkbox"/>	<input type="checkbox"/>	US 5313095 A	19940517	12	Multiple-chip semiconductor device and a method of manufacturing the same	257/672	257/666; 257/676;		Tagawa, Tomohide et al	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 531309
3	<input type="checkbox"/>	<input type="checkbox"/>	JP 05299576 A	19931112	12	Multi-chip type semiconductor device having thickness of controlling external				KAWAKAMI, T et al	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 531309

GoDetailsImage

Ready

NUM